PDS BOM-PMP11312REVA.xls
None
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N/A

PMP11312 REV A Bill of Materials

LogicalDesignator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		Use PMP11312 REVA	Any	Printed Circuit Board	
C11, C8	2	2.2uF	GRM188R61C225KAAD	MuRata	CAP, CERM, 2.2 µF, 16 V, +/- 10%, X5R, 0603	0603
C1, C9	2	1uF	C1005X5R1C105K050BC	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	0402
C7, C5, C2, C6	4	22pF	C1005C0G1H220J050BA	TDK	CAP, CERM, 22 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C4, C10, C33, C34, C45, C46, C35, C47, C74, C78	10	1000pF	C1005X7R1H102K	TDK	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
C3	1	3300pF	C1005X7R1H332K	TDK	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0402	0402
C21, C24, C18, C25, C28, C13, C15, C17, C20, C22, C12, C14, C16, C19, C23, C67, C68, C69, C70, C71	20	22uF	GRM31CR61C226KE15L	MuRata	CAP, CERM, 22 µF, 16 V, +/- 10%, X5R, 1206	1206
C51, C49, C53, C48, C50, C54, C79, C80, C85, C86, C88, C89	12	470uF	EEF-GX0E471R	Panasonic	CAP, Aluminum Polymer, 470 µF, 2.5 V, +/- 20%, 0.003 ohm, SMD_7.3x1.9x4.3mm SMD	SMD_7.3x1.9x4.3mm
C58, C64, C56, C59, C62, C65, C55, C57, C60, C61, C63, C66, C81, C82, C83, C84, C90, C91, C92, C93, C94, C95, C96, C97, C98, C99, C100, C101, C102, C103, C104, C105, C106, C107, C108, C109, C110, C111, C112, C113	40	100uF	JMK316BJ107ML-T	Taiyo Yuden	CAP, CERM, 100 µF, 6.3 V, +/- 20%, X5R, 1206	1206
C31, C26, C27, C72	4	3300pF	GRM188R71H332KA01D	MuRata	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0603	0603
C32, C29, C30, C73	4	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
C36, C37, C38, C75, C52, C114	6	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
C43, C42, C44, C77	4	0.1uF	06033C104JAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 5%, X7R, 0603	0603
C39, C40, C41, C76	4	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X5R, 0603	0603
C87	1	220uF	EMZA160ADA221MF80G	Chemi-Con	CAP, AL, 220 µF, 16 V, +/- 20%, 0.34 ohm, SMD	F80

LogicalDesignator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
FID1, FID2, FID3	3		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
J1, J2	2		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
P1	1		1715747	Phoenix Contact	Terminal Block, 5.08mm, 4x1, TH	Terminal Block, 5.08mm, 4x1, TH
P12, P13, P11	3		800-10-002-10-001000	Mill-Max	Header, 100mil, 2x1, TH	Header, 2x1, 100mil, TH
P2, P6, P3, P7, P4, P8, P5, P9	8		108-0740-001	Emerson Network Power	Standard Banana Jack, Uninsulated, 15A	Banana Jack
P10	1		N2510-6002-RB	3M	Header (shrouded), 100mil, 5x2, High-Temperature, Gold, TH	5x2 Shrouded header
L1, L2, L3, L4	4	150nH	PA2607.151NLT	Pulse Engineering	Inductor, Ferrite, 150 nH, 41 A, 0.00029 ohm, SMD	10.31x7.65mm
Q1	1	30V	FDMC7660	Fairchild Semiconductor	MOSFET, N-CH, 30 V, 40 A, QFN-8	QFN-8
R3, R4	2	100	ERJ-2RKF1000X	Panasonic	RES, 100, 1%, 0.1 W, 0402	0402
R25, R24, R28, R26, R27, R39	6	2.2	CRCW04022R20JNED	Vishay-Dale	RES, 2.2, 5%, 0.063 W, 0402	0402
R1, R2	2	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
R7	1	2.43k	CRCW04022K43FKED	Vishay-Dale	RES, 2.43 k, 1%, 0.063 W, 0402	0402
R21, R22, R43	3	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R16	1	4.64k	CRCW04024K64FKED	Vishay-Dale	RES, 4.64 k, 1%, 0.063 W, 0402	0402
R10	1	78.7k	CRCW040278K7FKED	Vishay-Dale	RES, 78.7 k, 1%, 0.063 W, 0402	0402
R8	1	22.6k	CRCW040222K6FKED	Vishay-Dale	RES, 22.6 k, 1%, 0.063 W, 0402	0402
R5	1	26.7k	CRCW040226K7FKED	Vishay-Dale	RES, 26.7 k, 1%, 0.063 W, 0402	0402
R6	1	9.31k	CRCW04029K31FKED	Vishay-Dale	RES, 9.31 k, 1%, 0.063 W, 0402	0402
R9	1	16.5k	CRCW040216K5FKED	Vishay-Dale	RES, 16.5 k, 1%, 0.063 W, 0402	0402
R11	1	61.9k	CRCW040261K9FKED	Vishay-Dale	RES, 61.9 k, 1%, 0.063 W, 0402	0402
R12, R17	2	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R20, R18, R19	3	24.3k	CRCW040224K3FKED	Vishay-Dale	RES, 24.3 k, 1%, 0.063 W, 0402	0402
R13	1	39k	CRCW040239K0JNED	Vishay-Dale	RES, 39 k, 5%, 0.063 W, 0402	0402
R14	1	150k	CRCW0402150KFKED	Vishay-Dale	RES, 150 k, 1%, 0.063 W, 0402	0402
R15	1	48.7k	CRCW040248K7FKED	Vishay-Dale	RES, 48.7 k, 1%, 0.063 W, 0402	0402
R23	1	121k	CRCW0402121KFKED	Vishay-Dale	RES, 121 k, 1%, 0.063 W, 0402	0402
R29, R30, R31, R40	4	1.00	CRCW04021R00FKED	Vishay-Dale	RES, 1.00, 1%, 0.063 W, 0402	0402
R35, R32, R33, R36, R34, R37, R41, R422	8	1.00	CRCW06031R00FKEA	Vishay-Dale	RES, 1.00, 1%, 0.1 W, 0603	0603
R38, R45	2	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R44	1	0.01	ERJ-M1WSF10MU	Panasonic	RES, 0.01, 1%, 1 W, 2512	2512
U1	1	TPS53647RTAR	TPS53647RTAR	Texas Instruments	4-Phase, D-CAP+TM Step-Down Buck Controller with NVM and PMBus Interface, RTA0040B	RTA0040B
U2, U3, U4, U5	4	CSD95372B	CSD95372BQ5M	Texas Instruments	Synchronous Buck NexFET Power Stage, DQP0012A	DQP0012A

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